Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSIII)

2SK2700

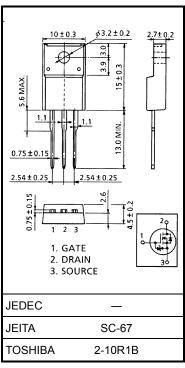
Chopper Regulator, DC–DC Converter and Motor Drive Applications

• Low drain—source ON resistance : RDS (ON) = 3.7 Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 2.6$ S (typ.)

• Low leakage current : $I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 720 \text{ V)}$ • Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA)}$

Absolute Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit
Drain-source voltage	Drain–source voltage		900	٧
Drain–gate voltage (R _{GS} = 20 kΩ)		V _{DGR}	900	V
Gate-source voltage		V _{GSS}	±30	V
Drain current	DC (Note 1)	I _D	3	Α
Diam current	Pulse (Note 1)	I _{DP}	9	А
Drain power dissipation	n (Tc = 25°C)	P _D	40	W
Single pulse avalanche	e energy (Note 2)	E _{AS}	295	mJ
Avalanche current		I _{AR}	3	А
Repetitive avalanche e	nergy (Note 3)	E _{AR}	4	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature ra	ange	T _{stg}	-55~150	°C



Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.125	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 60.0 mH, R_{G} = 25 Ω , I_{AR} = 3 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.

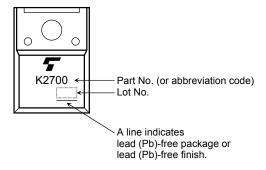
Electrical Characteristics (Ta = 25°C)

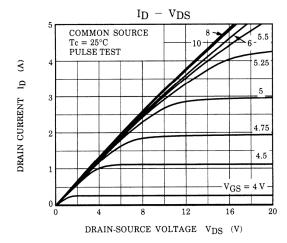
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V		_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	900	_	_	٧
Gate threshold v	/oltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 1.5 A	_	3.7	4.3	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 20 V, I _D = 1.5 A	0.65	2.6	_	S
Input capacitano	ce	C _{iss}		_	750	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	10	_	pF
Output capacita	t capacitance C _{oss}		_	70	_		
Switching time	Rise time	t _r	$V_{GS} \stackrel{10V}{\underset{0V}{\longrightarrow}} \stackrel{I_{D}=1.5A}{\underset{R_{L}=133\Omega}{\longrightarrow}} v_{out}$ $V_{DD} \stackrel{\vdots}{\rightleftharpoons} 200V$ $Duty \leq 1\%, \ t_{W}=10\mu s$	_	15	_	ns ns
	Turn-on time	t _{on}		_	55	_	
	Fall time	t _f		_	30	_	
	Turn–off time	t _{off}		_	110	_	
Total gate charge (gate–source plus gate–drain)		Qg	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 3 A		25	_	nC
Gate-source charge		Qgs			13		
Gate-drain ("miller") Charge		Q _{gd}			12		

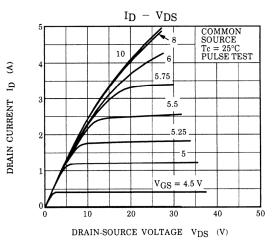
Source-Drain Ratings and Characteristics (Ta = 25°C)

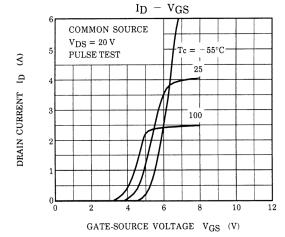
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	3	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	9	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 3 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	I _{DR} = 3 A, V _{GS} = 0 V		1100		ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 A / μs	_	7.2	_	μC

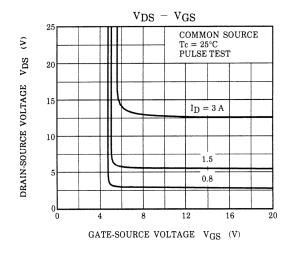
Marking

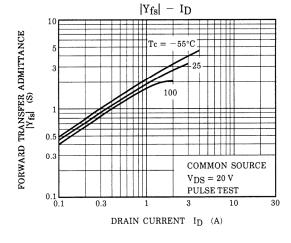


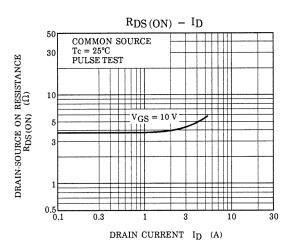




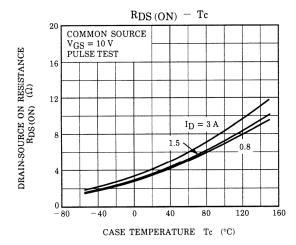


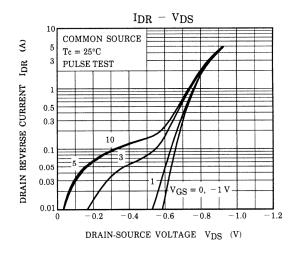


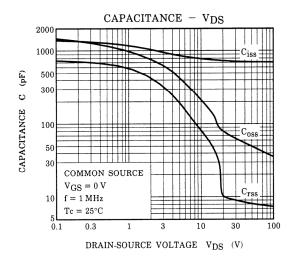


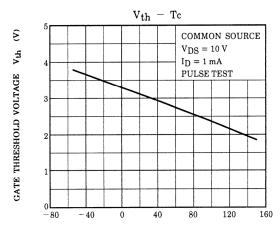


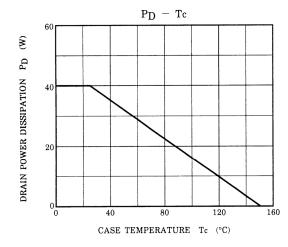
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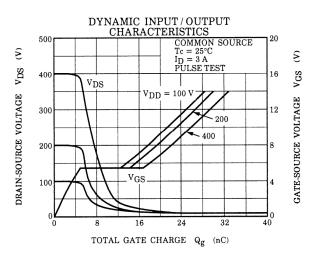




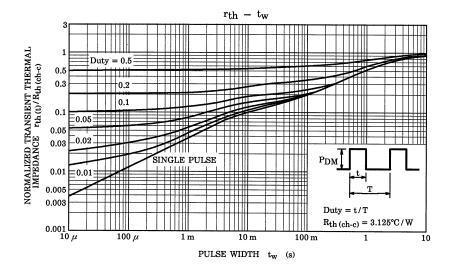


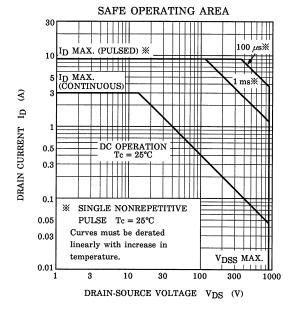


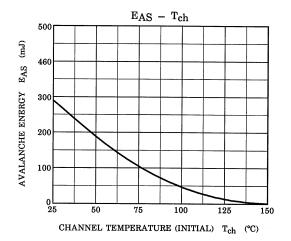


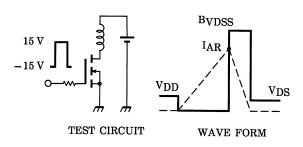


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$$R_G$$
 = 25 Ω
 V_{DD} = 90 V, L = 60 mH

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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